



Receipt

In the United States Patent and Trademark Office

In re the Application of:

Lee D. Whetsel

TI-20787.2

Serial No. 09/697,941

Art Unit: 2829

Filed: 10/26/2000

Examiner: Nguyen, Vinh P.

Title: Fault Tolerant Selection of Die on Wafer

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ORIGINALLY FILED

**Letter Requesting Corrected Filing Receipt To
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July 3, 2002

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Lawrence J. Bassuk, Reg. No. 29,043

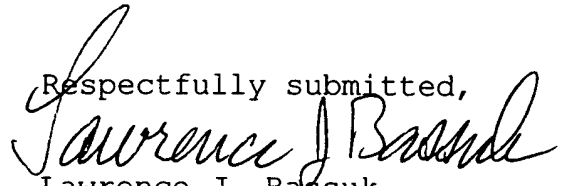
Please amend the Filing Receipt to read as follows:

--This application is a divisional of Application No.
09/416,562, filed October 12, 1999, now US 6,166,557; which was a
divisional of Application No. 08/741,457, filed October 31, 1996,
now US 5,994,912; which claimed priority from provisional
Application No. 60/008,138, filed October 31, 1995.--

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Applicant encloses a copy of the original Filing Receipt.

Respectfully submitted,



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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/697,941	10/26/2000	2858	710	TI-20787.2	41	2	2

FILING RECEIPT



OC000000005638136

Date Mailed: 12/26/2000



Lawrence J. Bassuk
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Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the PTO processes the reply to the Notice, the PTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Lee D. Whetsel, Allen, TX ;

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Continuing Data as Claimed by Applicant

THIS APPLICATION IS A DIV OF 09/416,562 10/12/1999 PAT 6,166,557

Foreign Applications

If Required, Foreign Filing License Granted 12/26/2000

Title

Fault tolerant selection of die on wafer

Preliminary Class

324

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